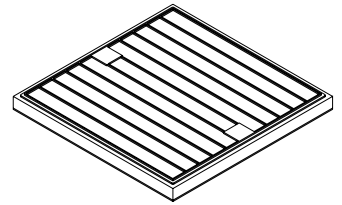


ODH5656TF.A2

OS-CORE® ThinGaAlP



Features:

- Polarity: n-side up
- Chip technology: Thinfilm
- Color: ● hyper red
- Chipsize: 56 mil x 56 mil

Ordering Information

Type
ODH5656TF.A2-MM-MM-1-C

Ordering Code
Q65112A7320

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min.	-40 °C
		max.	125 °C
Storage Temperature ¹⁾	T_{stg}	min.	-40 °C
		max.	125 °C
Recommended Die Storage Temperature ≤ 60% RH	$T_{stg\ die}$	max.	30 °C
Junction Temperature	T_j	max.	150 °C
Junction temperature for short time applications*	T_j	max.	175 °C
Forward Current $T_j = 25\text{ °C}$	I_F	min.	100 mA
		max.	1000 mA
Forward Current Pulsed $t \leq 10\text{ }\mu\text{s}$; $D = 0.005$; $T_j = 25\text{ °C}$	$I_{F\ pulse}$	max.	1500 mA
Reverse voltage ²⁾	V_R	Not designed for reverse operation	

*The median lifetime (L70/B50) for $T_j = 175\text{ °C}$ is 100h.

Characteristics

$I_F = 700\text{ mA}$; $T_j = 25\text{ °C}$

Parameter	Symbol		Values
Centroid Wavelength ³⁾ $I_F = 700\text{ mA}$	$\lambda_{\text{centroid}}$	min.	647 nm
		max.	665 nm
Forward Voltage ⁴⁾ $I_F = 700\text{ mA}$	V_F	min.	2.00 V
		typ.	2.10 V
		max.	2.40 V

Additional Information

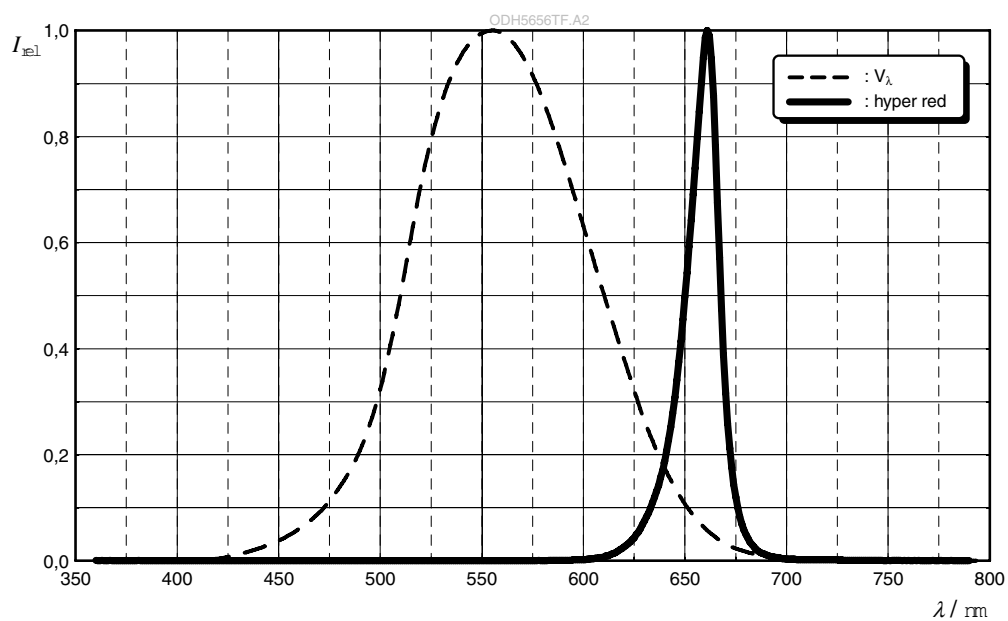
Die bonding	Metalization frontside	Metalization backside
Adhesive bonding	Gold	Gold

Binning Table ⁵⁾³⁾ $I_F = 700 \text{ mA}$

Radiant Intensity I_e a. u.	Centroid Wavelength		
	$\lambda_{\text{centroid}}$ nm		
	647 - 653	653 - 659	659 - 665
200 - 215	A10	B10	C10
215 - 220	A13	B13	C13
220 - 225	A16	B16	C16
225 - 230	A19	B19	C19
230 - 235	A22	B22	C22
235 - 240	A25	B25	C25
240 - 250	A28	B28	C28
250 - 265	A31	B31	C31
265 - 280	A34	B34	C34

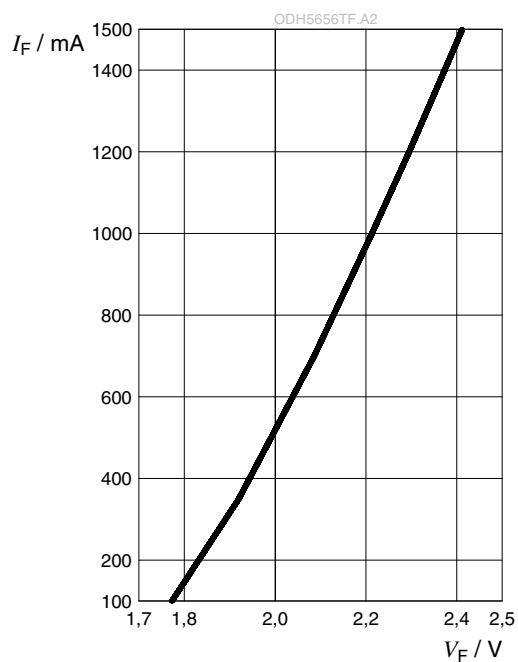
Relative Spectral Emission ⁶⁾

$I_{\text{rel}} = f(\lambda)$; $I_F = 700 \text{ mA}$; $T_S = 25^\circ \text{C}$



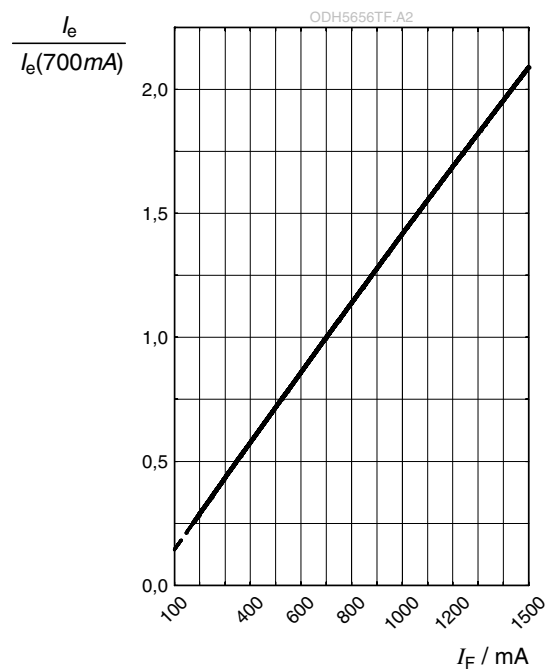
Forward current ^{6), 7)}

$$I_F = f(V_F); T_S = 25^\circ\text{C}$$



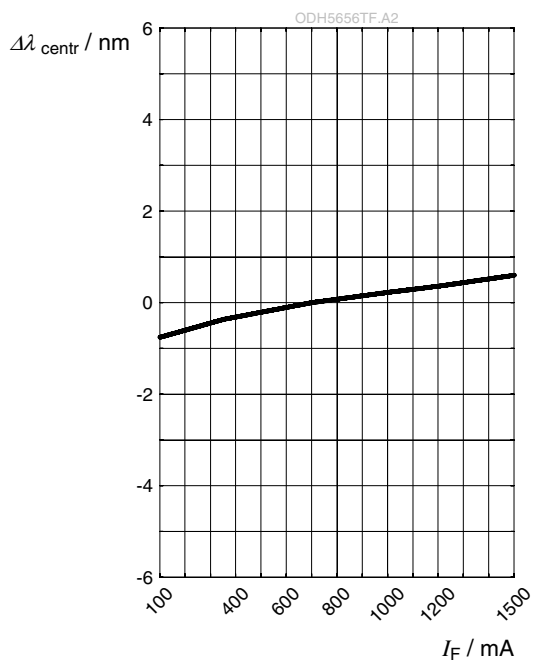
Relative Radiant Intensity ^{6), 7)}

$$I_E/I_E(700 \text{ mA}) = f(I_F); T_S = 25^\circ\text{C}$$



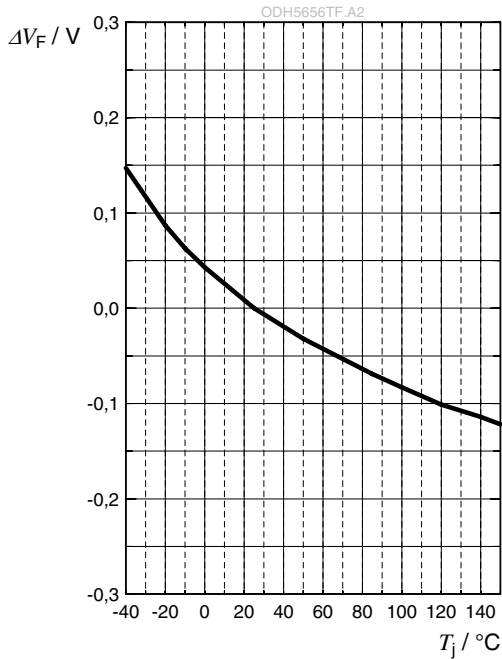
Centroid Wavelength ⁶⁾

$$\Delta\lambda_{\text{centr}} = f(I_F); T_S = 25^\circ\text{C}$$



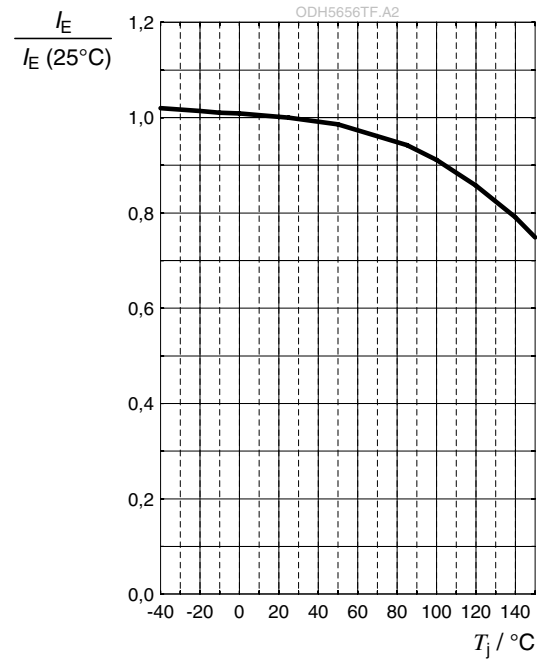
Forward Voltage ⁶⁾

$$\Delta V_F = V_F - V_F(25^\circ\text{C}) = f(T_j); I_F = 700\text{ mA}$$



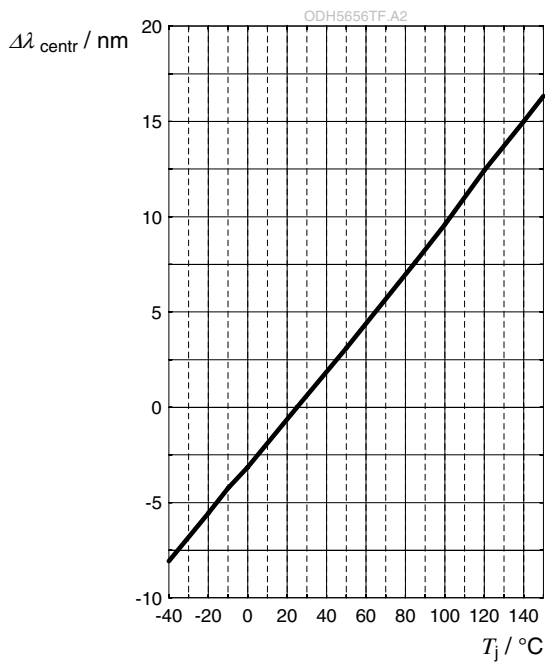
Relative Radiant Intensity ⁶⁾

$$I_E / I_E(25^\circ\text{C}) = f(T_j); I_F = 700\text{ mA}$$

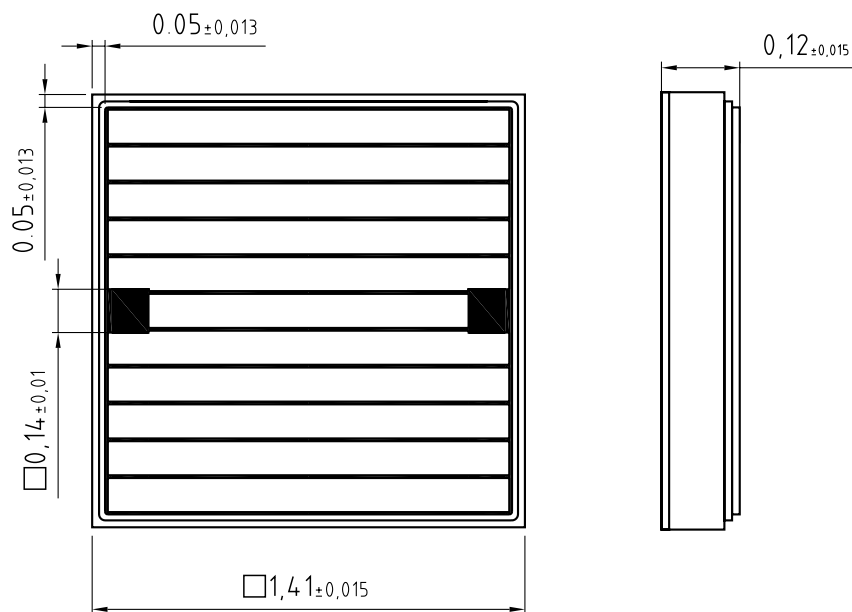


Centroid Wavelength ⁶⁾

$$\Delta \lambda_{\text{centr}} = \lambda_{\text{centr}} - \lambda_{\text{centr}}(25^\circ\text{C}) = f(T_j); I_F = 700\text{ mA}$$



Dimensional Drawing ⁸⁾



C63062-A6000-A145 -01

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Glossary

- 1) **Shelf life:** Temperature refer solely to storage of finished LED product (Not valid for chip on die sheet).
- 2) **Reverse Operation:** Not designed for reverse operation. Continuous reverse operation can cause migration and damage of the device.
- 3) **Wavelength:** The wavelength is measured at a current pulse of typically 10 ms and with an internal reproducibility of ± 1 nm (with a coverage factor of $k = 3$).
- 4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 5 ms and with an internal reproducibility of ± 0.1 V (with a coverage factor of $k = 3$).
- 5) **Brightness:** Brightness values are measured during a current pulse of typically 10 ms and with an internal reproducibility of ± 8 % (with a coverage factor of $k = 3$).
- 6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.

